

Contents

List of Symbols and Abbreviations	xxi
1 Introduction	1
2 Theoretical Background	7
2.1 Thin Films and MEMS	7
2.1.1 Internal Structure of Solid Materials	7
2.1.2 Deposition of Thin-Films	8
2.1.3 Patterning of Thin Films	15
2.2 Thermal Properties of Silicon Oxide	20
2.2.1 Heat Capacity in Solid Materials	20
2.2.2 Thermal Conductivity Mechanisms in Dielectrics .	21
2.2.3 Role of Impurities for the Thermal Conductivity .	22
2.2.4 Heat Transport in Amorphous Dielectrics	23
2.2.5 State of the Art of Measurement Techniques . . .	25
2.3 Material Characterization of Silicon Carbide	29
2.3.1 Electrical Properties of SiC	29
2.3.2 Mechanical Properties of SiC	36
2.4 Reliability of Thin-Film Platinum Layers	46
2.4.1 Grain Growth and Element Diffusion	46
2.4.2 Electromigration	51
3 Experimental Methods	55
3.1 Material Fabrication	55

3.2	Thermal Properties of PECVD Silicon Dioxide	57
3.2.1	Thermal Conductivity Determination	57
3.2.2	FEM Aided Data Analysis	59
3.2.3	Heat Capacity Determination	62
3.2.4	Test Samples and Experimental Setup	64
3.3	Electrical Properties of LPCVD Silicon Carbide	75
3.3.1	Layer Resistivity using the Van der Pauw Method	75
3.3.2	Contact Resistivity using the CTLM Method	79
3.4	Mechanical Properties of LPCVD Silicon Carbide	82
3.4.1	Test Structure Design and Fabrication	82
3.4.2	Static Actuation of Single-Side Clamped Beams	87
3.4.3	Resonant Behavior of Single-Side Clamped Beams	97
3.4.4	Resonant Behavior of Double-Side Clamped Beams	103
3.5	Reliability Testing of Sputtered Platinum	105
3.5.1	Thin-Film Platinum at High Temperatures	105
3.5.2	Electromigration and Black's Equation	113
4	Results	119
4.1	Thermal Properties of Silicon Oxide	120
4.1.1	Thermal Conductivity	120
4.1.2	Heat Capacity	130
4.1.3	Summary	134
4.2	Electro-Mechanical Properties of Silicon Carbide	135
4.2.1	Specific Electrical Resistivity	136
4.2.2	Specific Contact Resistivity	138
4.2.3	Density Determination	140
4.2.4	Single-Side Clamped Resonant Measurements	141
4.2.5	Double-Side Clamped Resonant Measurements	143
4.2.6	Optical Measurements	145
4.2.7	Deflection vs. Voltage Measurements	148

4.2.8	Capacitance Measurements	149
4.2.9	High Temperature Resonance Measurements . . .	154
4.2.10	Summary	158
4.3	Reliability Characterization of Platinum	159
4.3.1	Stress-Migration and Diffusion Experiments	159
4.3.2	Electromigration Experiments	176
4.3.3	Interaction of Electro- and Stress-Migration	188
4.3.4	Summary	189
5	Conclusions	191
	Bibliography	201
	Appendix	229